

# SOT616-8

HVQFN24, plastic, thermally enhanced very thin quad; flat non-leaded package; 24 terminals; 0.5 mm pitch; 4 mm x 4 mm x 0.9 mm body

21 February 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN24
<b>Package type industry code</b>	HVQFN24
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-01-2016
<b>Manufacturer package code</b>	98ASA00474D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4	-	mm
package width	-	4	-	mm
seated height	-	0.9	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	



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2 Package outline

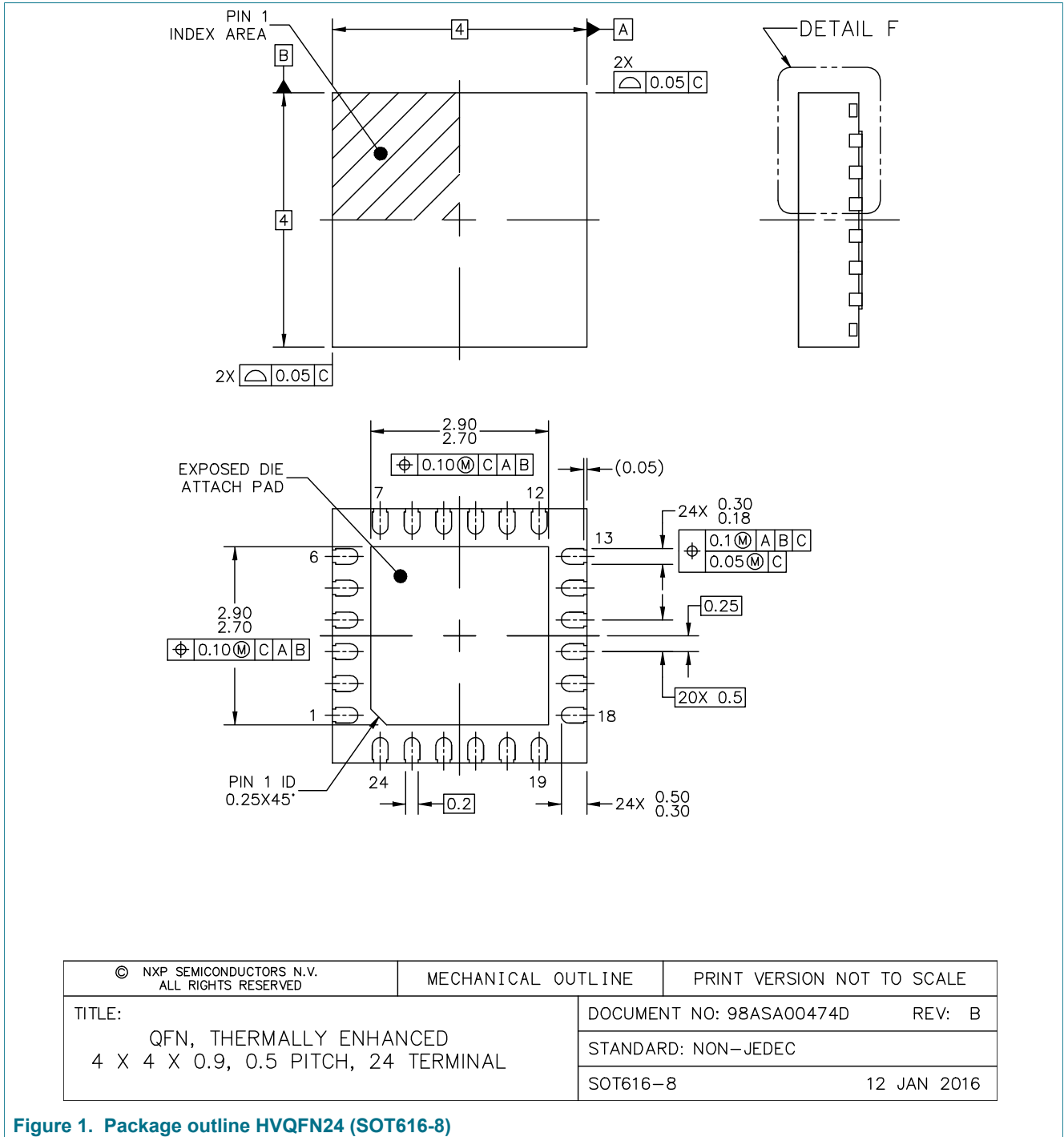


Figure 1. Package outline HVQFN24 (SOT616-8)

HVQFN24, plastic, thermally enhanced very thin quad; flat non-leaded package; 24 terminals; 0.5 mm pitch; 4 mm x 4 mm x 0.9 mm body

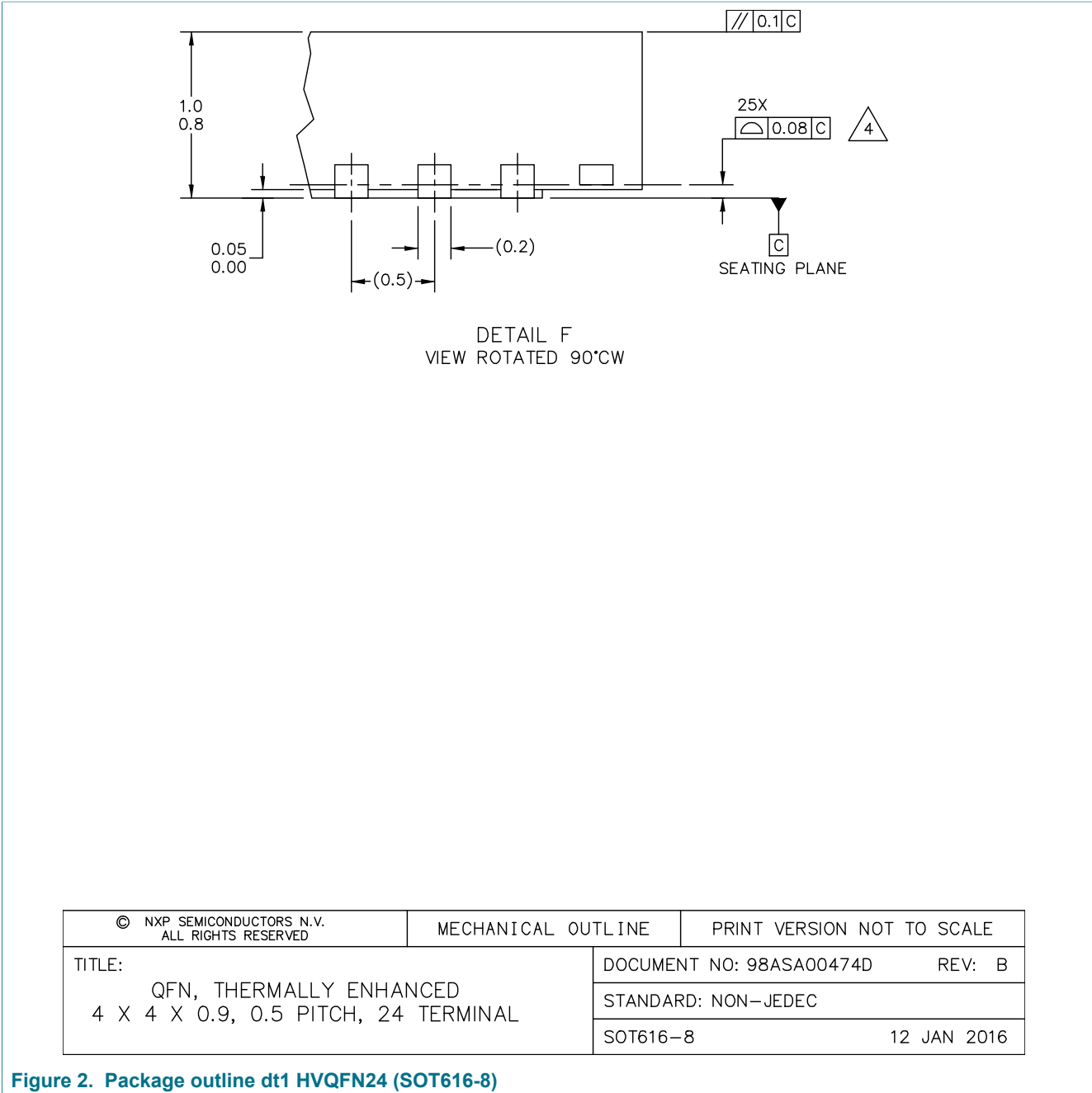



Figure 2. Package outline dt1 HVQFN24 (SOT616-8)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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TITLE: QFN, THERMALLY ENHANCED 4 X 4 X 0.9, 0.5 PITCH, 24 TERMINAL		DOCUMENT NO: 98ASA00474D	REV: B
		STANDARD: NON-JEDEC	
		SOT616-8	12 JAN 2016

Figure 3. Package outline note HVQFN24 (SOT616-8)

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### 3 Legal information

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